

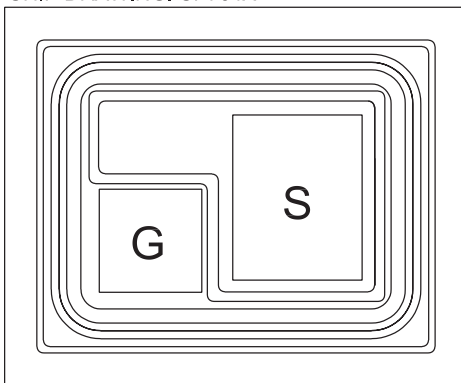
**PROCESS CP764X**  
**Small Signal MOSFET Transistor**  
**P-Channel Enhancement-Mode Transistor Chip**



**PROCESS DETAILS**

Process	EPITAXIAL PLANAR
Die Size	21.7 x 17.7 MILS
Die Thickness	5.5 MILS
Gate Bonding Pad Area	4.7 x 4.7 MILS
Source Bonding Pad Area	6.1 x 7.9 MILS
Top Side Metalization	Al-Si - 35,000Å
Back Side Metalization	Au - 9,000Å

**GEOMETRY**



BACKSIDE: DRAIN

R0

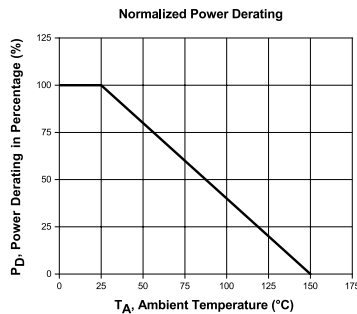
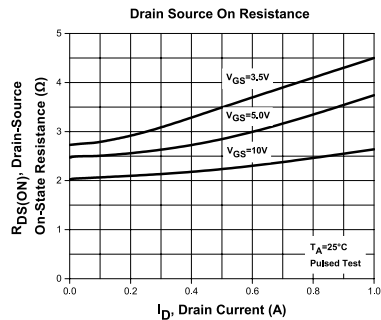
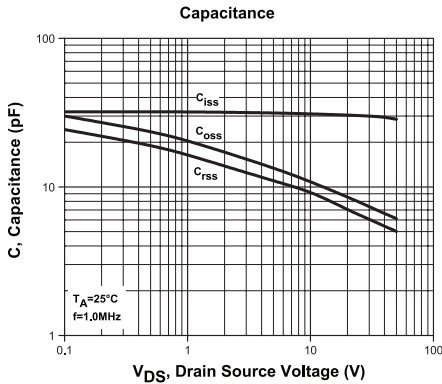
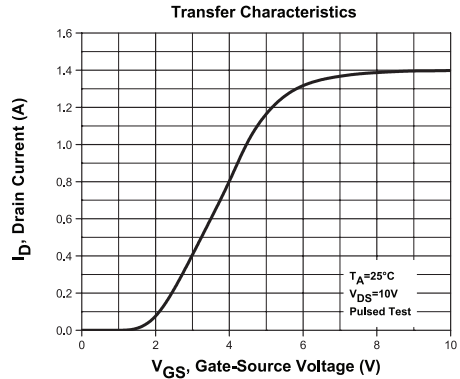
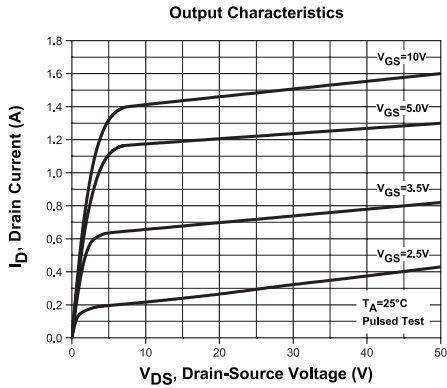
**GROSS DIE PER 6 INCH WAFER**  
 62,600

**PRINCIPAL DEVICE TYPES**

- CMLDM8002A
- CMPDM8002A
- CTLDM8002A-M621

# PROCESS CP764X

## Typical Electrical Characteristics



## BARE DIE PACKING OPTIONS

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### BARE DIE IN TRAY (WAFFLE) PACK

**CT:** Singulated die in tray (waffle) pack.  
(example: CP211-PART NUMBER-CT)

**CM:** Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).  
(example: CP211-PART NUMBER-CM)

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### UNSAWN WAFER

**WN:** Full wafer, unsawn, 100% tested with reject die inked.  
(example: CP211-PART NUMBER-WN)

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### SAWN WAFER ON PLASTIC RING

**WR:** Full wafer, sawn and mounted on plastic ring,  
100% tested with reject die inked.  
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:  
[www.centrasemi.com/bdspecs](http://www.centrasemi.com/bdspecs)

## OUTSTANDING SUPPORT AND SUPERIOR SERVICES



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### PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

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### DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

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### REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

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### CONTACT US

#### Corporate Headquarters & Customer Support Team

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[www.centrasemi.com](http://www.centrasemi.com)

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**Worldwide Distributors:**  
[www.centrasemi.com/wwdistributors](http://www.centrasemi.com/wwdistributors)

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